

Attorney Docket-B-64909 (013377/0058)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box PATENT APPLICATION

Assistant Commissioner

for Patents

Washington, D.C. 20231

Sir:

Transmitted herewith for filing is the patent application of:

Inventors:

Clyde Maxwell Guest, et al.

For:

SYSTEM AND METHOD FOR INSPECTING BUMPED WAFERS

Enclosed are:

1 pages of abstract

X Combined Declaration/

21 pages of specification

Power of Attorney

_5 pages of claims

X Assignment & Recordation Page

6 pages of informal drawings

Other: Check & Post Card Receipt

X Post Office Express Mail Certificate No. EL 524304376 US

The filing fee has been calculated as shown below:

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<u>For</u> :	No. Filed	<u>r</u>	No. Extra	<u>Rate</u>	<u>Fee</u>
Basic Fee					\$690.00
Total Claims	20 - 20 =		-0-	x \$ 18.	0.00
Indep. Claims	3 - 3=		-0-	x \$ 78.	0.00
Multiple deper	ndent claims	-none-		+ \$260.	0.00
	TOTAL		\$690.00		

Our check in the amount of \$690.00 in payment of the filing fee is enclosed.

The Commissioner of Patents and Trademarks is hereby authorized to charge any fee deficiency or to credit any fee overpayment relating to this matter to Deposit Account No. 01-0657. A duplicate copy of this sheet is enclosed.

Respectfully submitted

Date: August 3, 2000

Christopher J. Rourk Attorney for Applicant Registration No. 39, 348

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VIA EXPRESS MAIL

BOX PATENT APPLICATION Assistant Commissioner for **Patents** Washington, D. C. 20231

EXPRESS MAIL CERTIFICATE OF MAILING UNDER 37 C.F.R. 1.10

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Date of Deposit: August 3, 2000
I hereby certify that the papers enclosed herein are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 C.F.R. 1.10 on the date indicated above and addressed to: BOX PATENT APPLICATION, Assistant Commissioner of Patents, Washington, D.C. 20231.

Signature